Panasonic

ideas for life



Header

For board-to-FPC

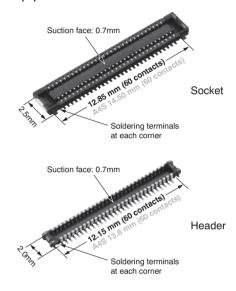
Narrow pitch connectors (0.35mm pitch)

A35S Series

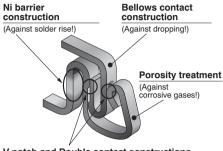
FEATURES

1. Small size (Terminal pitch: 0.35 mm, width: 2.5 mm and Mated height: 0.8

When mated, the footprint is reduced by approx. 10% from A4S series (60 pin contacts), contributing to the functionality enhancement and size reduction of end equipment.



2. "TOUGH CONTRCT ROVANCED" ensures high resistance to various environments in lieu of its spacesaving footprint.



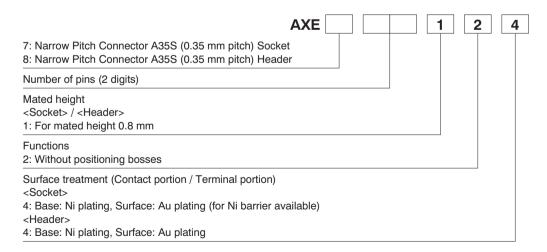
V notch and Double contact constructions (Against foreign particles and flux!)

- 3. Low-profile connector with up to 120 pin contacts
- 4. Soldering terminals at each corner enhance mounting strength.
- 5. Simple lock structure provides tactile feedback to ensure excellent mating/unmating operation feel.
- 6. Gull-wing-shaped terminals to facilitate visual inspections.

APPLICATIONS

Suitable for board-to-FPC connections in mobile equipment that requires size and thickness reduction and functionality enhancement.

ORDERING INFORMATION



PRODUCT TYPES

Mated height	Number of pins	Part n	umber	Packing		
		Socket	Header	Inner carton (1-reel)	Outer carton	
0.8mm	24	AXE724124	AXE824124		10,000 pieces	
	30	AXE730124	AXE830124			
	34	AXE734124	AXE834124			
	44	AXE744124	AXE844124	E 000 pieses		
	50	AXE750124	AXE850124	5,000 pieces		
	60	AXE760124	AXE860124			
	100	AXE700124	AXE800124			
	120	AXE7A2124	AXE8A2124			

Notes: 1. Order unit:

For volume production: in 1-inner carton (1-reel) units
Samples for mounting check: in 50-connector units. Please contact our sales office.

2. Please contact us for connectors having a number of pins other than those listed above.

SPECIFICATIONS

1. Characteristics

Item		Specifications	Conditions				
	Rated current	0.25A/pin contact (Max. 4 A at total pin contacts)					
Electrical characteristics	Rated voltage	60V AC/DC					
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.				
	Insulation resistance	Min. 1,000M Ω (initial)	Using 250V DC megger (applied for 1 min.)				
	Contact resistance	Max. 100mΩ	Based on the contact resistance measurement method specified by JIS C 5402.				
	Composite insertion force	Max. 0.981N/pin contacts × pin contacts (initial)					
Mechanical	Composite removal force	Min. 0.165N/pin contacts × pin contacts					
characteristics	Contact holding force (Socket contact)	Min. 0.20N/pin contacts	Measuring the maximum force. As the contact is axially pull out.				
	Ambient temperature	-55°C to +85°C	No freezing at low temperatures. No dew condensation.				
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering				
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron				
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.				
	Thermal shock resistance (header and socket mated)		Conformed to MIL-STD-202F, method 107G				
Environmental characteristics		5 cycles, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Order Temperature (°C) Time (minutes) 1 −55-3 30 2 ∫ Max. 5 3 85+3 30 4 ∫ Max. 5 −55-3 Max. 5				
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Bath temperature 40±2°C, humidity 90 to 95% R.H.				
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Bath temperature 35±2°C, saltwater concentration 5±1%				
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 100m $Ω$	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.				
Lifetime characteristics	Insertion and removal life	30 times	Repeated insertion and removal speed of max. 200 times/ hours				
Unit weight		60 pin contact type: Socket: 0.03 g Header: 0.02 g					

2. Material and surface treatment

Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	
Contact and Post	Copper alloy	Contact portion: Base: Ni plating, Surface: Au plating Terminal portion: Base: Ni plating, Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating, Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating, Surface: Au plating (except the terminal tips)

2 ds_65318_en_a35s: 311012J

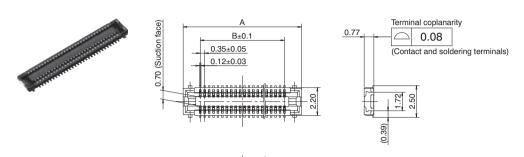
DIMENSIONS

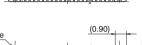
Interested in CAD data? You can obtain CAD data for all products with a CAD Data mark from your local Panasonic Electric Works representative.

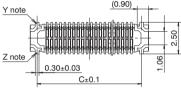


(Unit: mm)

Socket (Mated height: 0.8 mm)







General tolerance: ±0.2

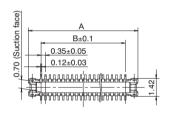
Dimension table (mm)

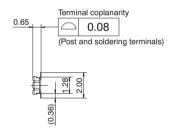
Number of pins/ dimension	А	В	С
24	6.55	3.85	5.45
30	7.60	4.90	6.50
34	8.30	5.60	7.20
50	11.10	8.40	10.00
60	12.85	10.15	11.75
64	13.55	10.85	12.45
100	19.85	17.15	18.75
120	23.35	20.65	22.25

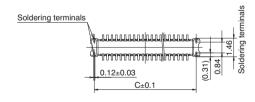
Note: Since the soldering terminals has a single-piece construction, sections Y and Z are electrically connected.

Header (Mated height: 0.8 mm)









General tolerance: ±0.2

Dimension table (mm)

Number of pins/ dimension	А	В	С	
24	5.85	3.85	5.25	
30	6.90	4.90	6.30	
34	7.60	5.60	7.00	
50	10.40	8.40	9.80	
60	12.15	10.15	11.55	
64	12.85	10.85	12.25	
100	19.15	17.15	18.55	
120	22.65	20.65	22.05	

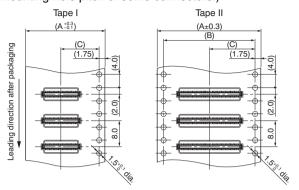
• Socket and Header are mated



EMBOSSED TAPE DIMENSIONS (Unit: mm)

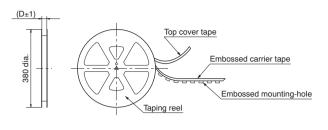
· Specifications for taping

(In accordance with JIS C 0806-1999. However, not applied to the mounting-hole pitch of some connectors.)



Specifications for the plastic reel

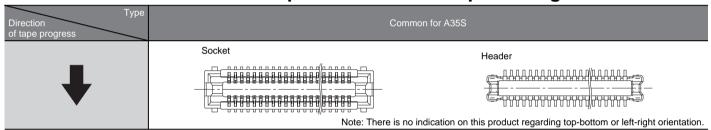
(In accordance with EIAJ ET-7200B.)



• Dimension table (Unit: mm)

Type/Mated height	Number of pins	Type of taping	А	В	С	D	Quantity per reel
	24	Tape I	16.0		7.5	17.4	5,000
Common for sockets and headers	30 to 64	Tape I	24.0	-	11.5	25.4	5,000
0.8mm	100	Tape II	32.0	28.4	14.2	33.4	5,000
	120	Tape II	44.0	40.4	20.2	45.4	5,000

Connector orientation with respect to embossed tape feeding direction



NOTES

■ Design of PC board patterns

Conduct the recommended foot pattern design, in order to preserve the mechanical strength of terminal solder areas.

■ Recommended PC board and metal mask patterns

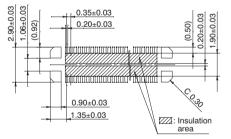
Connectors are mounted with high pitch density, intervals of 0.35 mm, 0.4 mm or 0.5 mm.

In order to reduce solder bridges and other issues make sure the proper levels of solder is used.

The figures to the right are recommended metal mask patterns. Please use them as a reference.

Socket (Mated height: 0.8 mm)

Recommended PC board pattern (TOP VIEW)

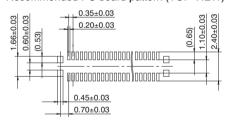


Recommended metal mask opening pattern Metal mask thickness: When 120µm (Terminal opening ratio: 70%) (Metal-part opening ratio: 100%)

0.35±0.01 0.18±0.01 0.18±0.01 0.20027 0.30±0.01 0.90±0.01

• Header (Mated height: 0.8 mm)

Recommended PC board pattern (TOP VIEW)



Recommended metal mask opening pattern

Metal mask thickness: When 120µm (Terminal opening ratio: 70%) (Metal-part opening ratio: 100%)



For Cautions for Use, see the "GENERAL NOTES ON USING ADVANCED SERIES NARROW-PITCH CONNECTORS" of the Connector Technical Information. For other details, please verify with the product specification sheets.